

FIG. 1

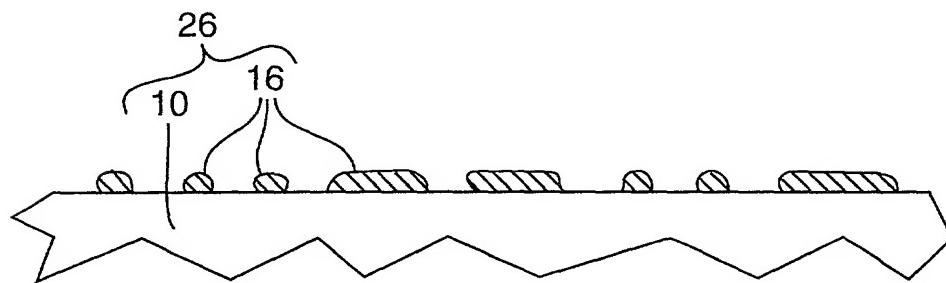


FIG. 2

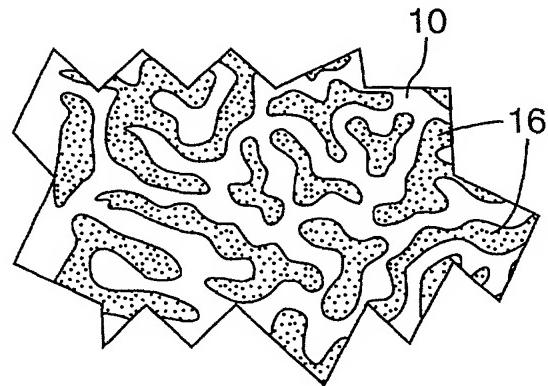
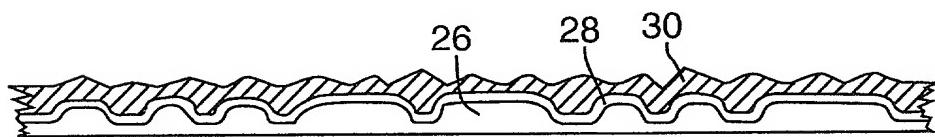
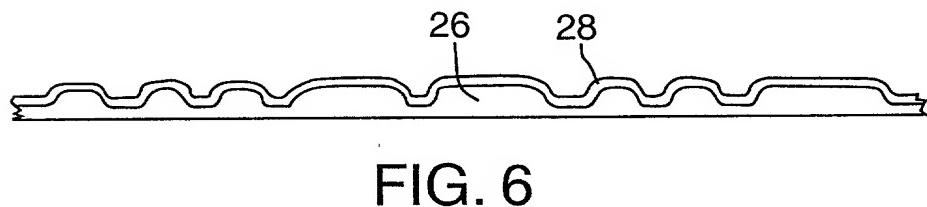
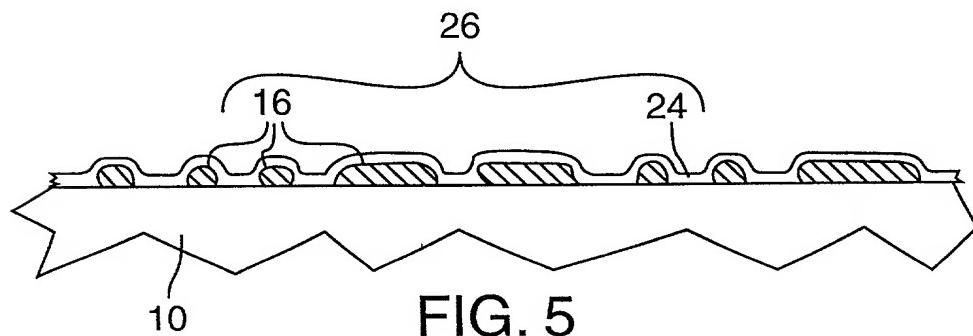
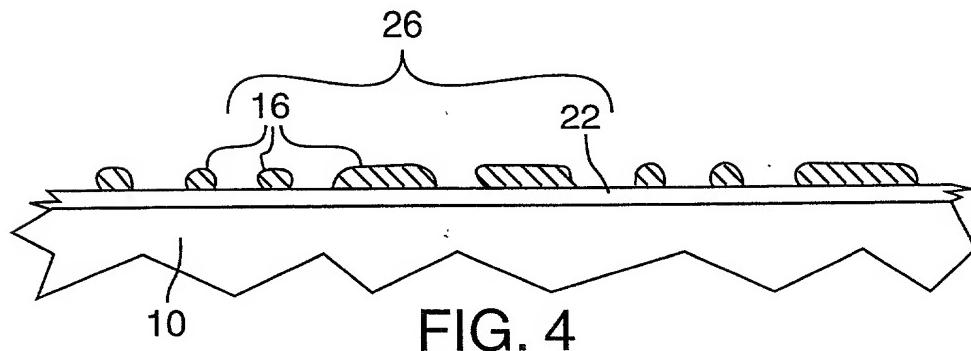


FIG. 3



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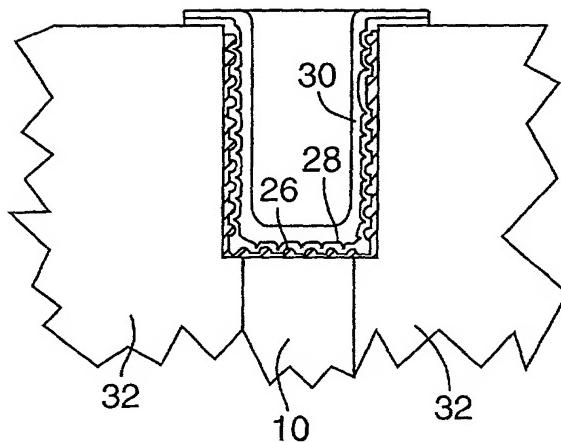


FIG. 8A

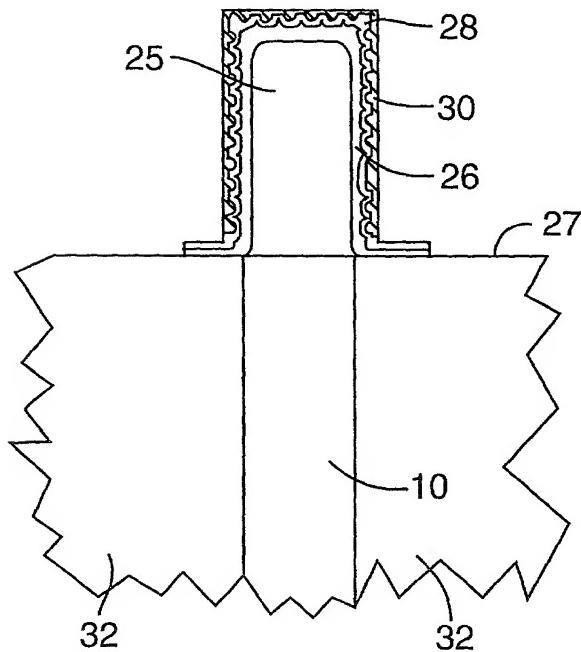


FIG. 8B

FIG. 9A

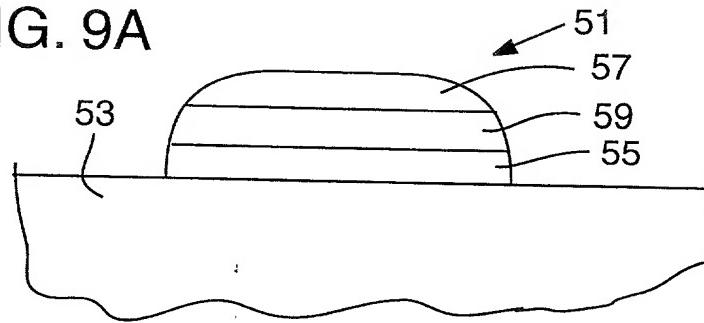


FIG. 9B

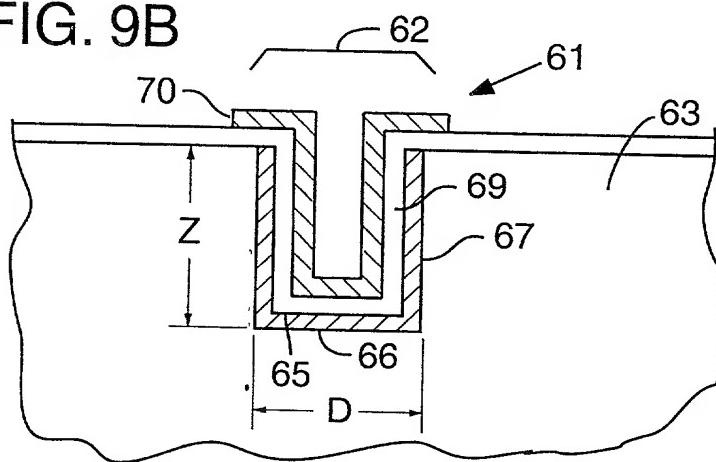


FIG. 9C

